



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

VICTOR TAN CHER 'KHNG
LEE KIAN CHAI

Serial No. 10/023,049

Art Unit: 2822

Filing Date: 12/20/2001

Examiner: Graybill, David E.

For: Semiconductor Package Having
Substrate With Multi-Layer
Metal Bumps

Attorney Docket No. 00-1117

**AMENDMENT SUBMITTED WITH REQUEST FOR CONTINUED
EXAMINATION (RCE) UNDER 37 CFR 1.114**

July 19, 2006

Mail Stop RCE
Commissioner For Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

This Amendment is in response to the Office Action dated 05/15/2006, having a statutory period for response set to expire on 08/15/2006. Please amend the application as follows.